SUBJECT: Characteristics for Thermal Silicon Compound
"ShinEtsu G746".

INTRODUCTION:
When the RF module is mounted onto a heat sink of an equipment, thermal compound to get heat sinking should be applied between the modules fin and the heat sink. Following thermal compound is recommended.

G746 ShinEtsu Chemical Industry Co., Ltd.

ADVANTAGE:
1. "ShinEtsu G746" has excellent thermal conductivity and which is 3 times improved compared to previous type.
2. "ShinEtsu G746" has wide range of usable temperature.

GENERAL CHARACTERISTICS:
1. Weight ratio: 2.66 @25deg.C
2. Thermal conductivity: 1.6x10E-3 (cal/cm-sec-deg.C)
3. Resistance : 1.2x10E14 (ohm-cm)
4. Temperature range: -50 to +150deg.C
(Above parameters will be subject to change by ShinEtsu Chemical Industry Co., Ltd.)

PRECAUTIONS:
Concerning to handling and storage "ShinEtsu G746" and details of characteristics, please contact ShinEtsu Chemical Industry Co., Ltd. (Japan)